

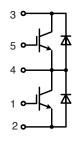
### **Advance Technical Data**

## FII24N17AH1

# High Voltage IGBT Phase-Leg

## FII24N170AH1

ISOPLUS i4-PAC™ Package

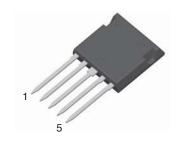


IGBT					
Symbol	Conditions	Maximum F	Maximum Ratings		
V <sub>CES</sub>	T <sub>vJ</sub> = 25°C to 150°C	1700	V		
V <sub>GES</sub>	Continuous	± 20	V		
$V_{\text{GEM}}$	Transient	± 30	V		
I <sub>C25</sub>	$T_C = 25^{\circ}C$	18	Α		
I <sub>C90</sub>	$T_C = 90^{\circ}C$	11	Α		
I <sub>CM</sub>		75	Α		
RBSOA	$V_{GE}$ = +15 V; $R_{G}$ = 5 $\Omega$ ; $T_{VJ}$ = 125°C Clamped inductive load; $V_{clamp}$ = 1360V	50	Α		
P <sub>c</sub>	T <sub>C</sub> = 25°C	140	W		

Symbol	Conditions (T -	Characteristic Values $\Gamma_{VI} = 25^{\circ}\text{C}$ unless otherwise specified)			
	(·₩ –	min.	typ.	max.	mou
V <sub>CE(sat)</sub>	$I_{\rm C} = 16 \text{ A}; V_{\rm GE} = 15 \text{ V}$ $T_{\rm VJ} = 125^{\circ}\text{C}$		4.5 4.8	6.0	V V
$V_{\text{GE(th)}}$	$I_{_{\mathrm{C}}}$ = 250 $\mu$ A; $V_{_{\mathrm{GE}}}$ = $V_{_{\mathrm{CE}}}$	3.0		5.0	V
I <sub>CES</sub>	$V_{CE} = 0.8 \ V_{CES}; V_{GE} = 0 \ V_{VJ} = 125^{\circ}C$			100 1.5	μA mA
I <sub>GES</sub>	$V_{CE} = 0 \text{ V}; V_{GE} = \pm 20 \text{ V}$			±100	nA
$egin{array}{l} oldsymbol{t}_{d(on)} \ oldsymbol{t}_{r} \ oldsymbol{t}_{d(off)} \ oldsymbol{t}_{f} \ oldsymbol{E}_{off} \end{array}$	Inductive load $\begin{aligned} &V_{_{CE}}=600\text{ V; }I_{_{C}}=24\text{ A}\\ &V_{_{GE}}=\pm15\text{ V; }R_{_{G}}=39\Omega \end{aligned}$		48 60 200 45 1.1		ns ns ns ns mJ
t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> E <sub>on</sub> E <sub>off</sub>	Inductive load, $T_{VJ}$ = 125°C $V_{CE}$ = 600 V; $I_{C}$ = 24 A $V_{GE}$ = ±15 V; $R_{G}$ = 39 $\Omega$		40 60 220 55 2.5 1.7		ns ns ns ns mJ mJ

Note: All characteristic values and ratings refer to a single IGBT or diode except  $V_{\rm CES}$ ,  $I_{\rm CES}$  and  $C_{\rm oes}$ .

 $I_{C25} = 18 A$   $V_{CES} = 1700 V$  $V_{CE(sat)} = 6.0 V$ 



#### **Features**

- NPT³ IGBT
- low saturation voltage
- positive temperature coefficient for easy paralleling
- fast switching
- short tail current for optimized performance in resonant circuits
- SONIC-FRD™ diode
- fast reverse recovery
- low operating forward voltage
- low leakage current
- ISOPLUS i4-PAC<sup>™</sup> package
- isolated back surface
- low coupling capacity between pins and heatsink
- enlarged creepage towards heatsink
- application friendly pinout
- low inductive current path
- high reliability
- industry standard outline
- UL registered, E 72873

#### **Applications**

- Single phaseleg
- buck-boost chopper
- H-bridge
  - power supplies
- induction heating
- four quadrant DC drives
- controlled rectifier
- Three phase bridge
  - AC drives
  - controlled rectifier

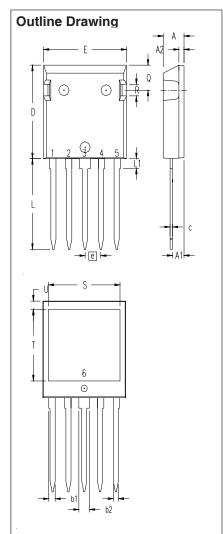


IGBT				
Symbol	Conditions	Characteristic Values min.   typ.   max.		
g <sub>fs</sub>	I <sub>C</sub> = 24 A, V <sub>CE</sub> = 10 V, Note 2	10	16	S
$\overline{\mathbf{Q}_{g}}$			105	nC
$\mathbf{Q}_{ge}$	$I_{\rm C}$ = 16 A, $V_{\rm GE}$ = 15 V, $V_{\rm CE}$ = 0.5 $V_{\rm CES}$		17	nC
$\mathbf{Q}_{gc}$			30	nC
C <sub>ies</sub>			2400	pF
C <sub>oes</sub>	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$		150	pF
$\mathbf{C}_{res}$			30	pF
R <sub>thJC</sub>				0.9 K/W
R <sub>thCK</sub>			0.6	K/W

Diode					
Symbol	Conditions	Maximum Ratings			
I <sub>F25</sub>	$T_C = 25^{\circ}C$		24		Α
I <sub>F90</sub>	$T_C = 90^{\circ}C$		14		Α
Symbol	Conditions	Characteristic Values min.   typ.   max.			
V <sub>F</sub>	I <sub>F</sub> = 20 A T <sub>VJ</sub> = 125°C		2.5 2.5	2.95	V V
I <sub>RM</sub>	$I_F = 20 \text{ A}; \text{ di}_F/\text{dt} = -450 \text{ A}/\mu\text{s}; T_{VJ} = 125^{\circ}\text{C}$ $V_R = 1200 \text{ V}; V_{GE} = 0 \text{ V}$		23 230		A ns
R <sub>thJC</sub>			1.6	K/W	

Component					
Symbol	Conditions	Maximum Ratings			
T <sub>VJ</sub>		-55+150 -55+125	°C °C		
V <sub>ISOL</sub>	$I_{ISOL} \le 1 \text{ mA}$ ; 50/60 Hz	2500	V~		
F <sub>c</sub>	mounting force with clip	20120	N		

Symbol	Conditions	Cha	Characteristic Values		
		min.	typ.	max.	
C <sub>p</sub>	coupling capacity between shorted pins and mounting tab in the case		40	pF	
d <sub>s</sub> ,d <sub>A</sub> d <sub>s</sub> ,d <sub>A</sub>	pin - pin pin - backside metal	1.7 5.5		mm mm	
Weight			9	g	



MYZ	INCH	IES	MILLIN	/ETERS
2114	MIN	MAX	MIN	MAX
Α	.190	.205	4.83	5.21
A1	.102	.118	2.59	3.00
A2	.046	.085	1.17	2.16
b	.045	.055	1.14	1.40
b1	.058	.068	1.47	1.73
b2	.100	.110	2.54	2.79
С	.020	.029	0.51	0.74
D	.819	.840	20.80	21.34
E	.770	.799	19.56	20.29
е	.150	BSC	3.81	BSC
L	.780	.840	19.81	21.34
L1	.083	.102	2.11	2.59
Q	.210	.244	5.33	6.20
R	.100	.180	2.54	4.57
S	.660	.690	16.76	17.53
Т	.590	.620	14.99	15.75
U	.065	.080	1.65	2.03

IXYS MOSFETs and IGBTs are covered by 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 one or moreof the following U.S. patents: 4,850,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405B2 6,759,692 6,759,692 6,704,645 6,769,692 6,769,69

0.6

K/W

 $\mathbf{R}_{\underline{\text{thCS}}}$